

OP200* PRODUCT PAGE QUICK LINKS

Last Content Update: 03/28/2017

COMPARABLE PARTS

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DOCUMENTATION

Application Notes

- AN-649: Using the Analog Devices Active Filter Design Tool

Data Sheet

- OP200: Dual Low Offset, Low Power Operational Amplifier Data Sheet
- OP200: Military Data Sheet

TOOLS AND SIMULATIONS

- OP200 SPICE Macro Models

DESIGN RESOURCES

- OP200 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

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REVISION HISTORY

3/2017—Rev. F to Rev. G

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10/2015—Rev. E to Rev. F

Changes to General Description	1
Changes to Ordering Guide	16

9/2012—Rev. D to Rev. E

Changed Table 2 Conditions from $V_S = 15\text{ V}$ to $V_S = \pm 15\text{ V}$	4
Updated Outline Dimensions	15
Changes to Ordering Guide	16

2/2009—Rev. C to Rev. D

Change to Large Signal Voltage Gain, Table 2	4
Changes to Ordering Guide	16

8/2008—Rev. B to Rev. C

Updated Format	Universal
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2/2004—Rev. A to Rev. B.

OP200F Deleted.....	Universal
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4/2002—Rev. 0 to Rev. A.

Edits to Features.....	1
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Edits to Ordering Information	1
Edits to Pin Connections.....	1
Edits to Absolute Maximum Ratings	2
Edits to Package Type	2

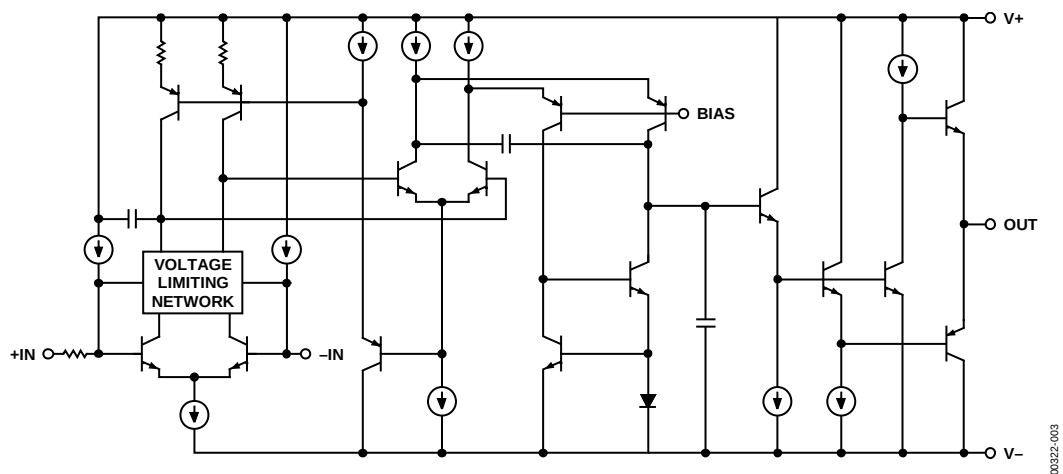


Figure 3. Simplified Schematic (One of Two Amplifiers Shown)

SPECIFICATIONS

ELECTRICAL CHARACTERISTICS

$V_S = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 1.

Parameter	Symbol	Conditions	OP200A/OP200E			OP200G			Unit
			Min	Typ	Max	Min	Typ	Max	
INPUT CHARACTERISTICS									
Input Offset Voltage	V _{OS}			25	75		80	200	μV
Long-Term Input Voltage Stability				0.1			0.1		μV/mo
Input Offset Current	I _{OS}	V _{CM} = 0 V		0.05	1.0		0.05	3.5	nA
Input Bias Current	I _B	V _{CM} = 0 V		0.1	2.0		0.1	5.0	nA
Input Noise Voltage	e _n p-p	0.1 Hz to 10 Hz		0.5			0.5		μV p-p
Input Noise Voltage Density ¹	e _n	f ₀ = 10 Hz		22	36		22		nV/√Hz
		f ₀ = 1000 Hz		11	18		11		nV/√Hz
Input Noise Current	i _n p-p	0.1 Hz to 10 Hz		15			15		pA p-p
Input Noise Current Density	i _n	f ₀ = 10 Hz		0.4			0.4		pA/√Hz
Input Resistance Differential Mode	R _{IN}			10			10		MΩ
Input Resistance Common Mode	R _{INCM}			125			125		GΩ
Large Signal Voltage Gain	A _{VO}	V _O = ±10 V							
		R _L = 10 kΩ	5000	12,000		3000	7000		M/mV
		R _L = 2 kΩ	2000	3700		1500	3200		M/mV

¹ Sample tested.

$V_S = \pm 15\text{ V}$, $-55^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ for OP200A, unless otherwise noted.

Table 2.

OP200A						
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Input Offset Voltage	V _{OS}			45	125	μV
Average Input Offset Voltage Drift	TCV _{OS}			0.2	0.5	μV/°C
Input Offset Current	I _{OS}	V _{CM} = 0 V		0.15	2.5	nA
Input Bias Current	I _B	V _{CM} = 0 V		0.9	5.0	nA
Large Signal Voltage Gain	A _{VO}	V _O = 10 V				
		R _L = 10 kΩ	3000	9000		V/mV
		R _L = 2 kΩ	1000	2700		V/mV
Input Voltage Range ¹	IVR		±12	±12.5		V
Common-Mode Rejection Ratio	CMRR	V _{CM} = ±12 V	115	130		dB
Capacitive Load Stability		A _v = 1		8		nF
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	V _S = 3 V to 18 V		0.2	3.2	μV/V
Supply Current Per Amplifier	I _{SY}	No load		600	775	μA
OUTPUT CHARACTERISTICS						
Output Voltage Swing	V _O	R _L = 10 kΩ	±12	±12.4		V
		R _L = 2 kΩ	±11	±12		V

¹ Guaranteed by CMRR test.

$V_S = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 3.

Parameter	Symbol	Conditions	OP200A/OP200E			OP200G			Unit
			Min	Typ	Max	Min	Typ	Max	
INPUT CHARACTERISTICS									
Input Voltage Range ¹	IVR	$V_{CM} = \pm 12\text{ V}$ $V_O = 20\text{ V p-p}$, $f_o = 10\text{ Hz}$	± 12	± 13		± 12	± 13		V
Common-Mode Rejection Ratio	CMRR		120	135		110	130		dB
Channel Separation ²	CS		123	145		123	145		dB
Input Capacitance	C_{IN}	$A_V = 1$, no oscillations		3.2			3.2		pF
Capacitive Load Stability				10			10		nF
POWER SUPPLY									
Power Supply Rejection Ratio	PSRR	$V_S = \pm 3\text{ V to } \pm 18\text{ V}$		0.4	1.8		0.6	5.6	$\mu\text{V/V}$
Supply Current Per Amplifier	I_{SY}	No load		570	725		570	725	μA
OUTPUT CHARACTERISTICS									
Output Voltage Swing	V_O	$R_L = 10\text{ k}\Omega$	± 12	± 12.6		± 12	± 12.6		V
		$R_L = 2\text{ k}\Omega$	± 11	± 12.2		± 11	± 12.2		V
DYNAMIC PERFORMANCE									
Slew Rate	SR	$A_V = 1$	0.1	0.15		0.1	0.15		V/ μs
Gain Bandwidth Product	GBP			500			500		kHz

¹ Guaranteed by CMRR test.

² Guaranteed but not 100% tested.

$V_S = \pm 15\text{ V}$, $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, unless otherwise noted.

Table 4.

Parameter	Symbol	Conditions	OP200E			OP200G			Unit
			Min	Typ	Max	Min	Typ	Max	
INPUT CHARACTERISTICS									
Input Offset Voltage	V _{OS}			35	100		110	300	μV
Average Input Offset Voltage Drift	TCV _{OS}			0.2	0.5		0.6	2.0	μV/°C
Input Offset Current	I _{OS}	V _{CM} = 0 V		0.08	2.5		0.1	6.0	nA
Input Bias Current	I _B	V _{CM} = 0 V		0.3	5.0		0.5	10.0	nA
Large-Signal Voltage Gain	A _{VO}	V _O = ±10 V							
		R _L = 10 kΩ	3000	10,000		2000	5000		V/mV
		R _L = 2 kΩ	1500	3200		1000	2500		V/mV
Input Voltage Range ¹	IVR		±12	±12.5		±12	±12.5		V
Common-Mode Rejection Ratio	CMRR	V _{CM} = ±12 V	115	130		105	130		dB
Capacitive Load Stability		A _V = 1, no oscillations		10			10		nF
POWER SUPPLY									
Power Supply Rejection Ratio	PSRR	V _S = ±3 V to ±18 V		0.15	3.2		0.3	10.0	μV/V
Supply Current Per Amplifier	I _{SY}	No load		600	775		600	775	μA
OUTPUT CHARACTERISTICS									
Output Voltage Swing	V _O	R _L = 10 kΩ	±12	±12.4		±12	±12.4		V
		R _L = 2 kΩ	±11	±12		±11	±12.2		V

¹ Guaranteed by CMRR test.

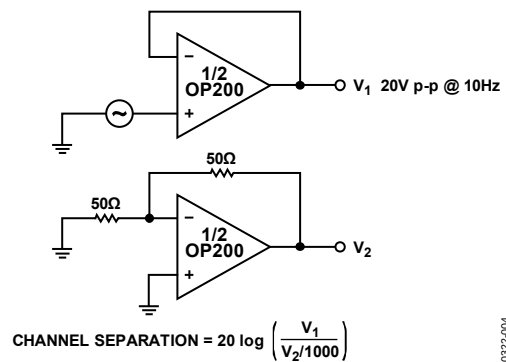


Figure 4. Channel Separation Test Circuit

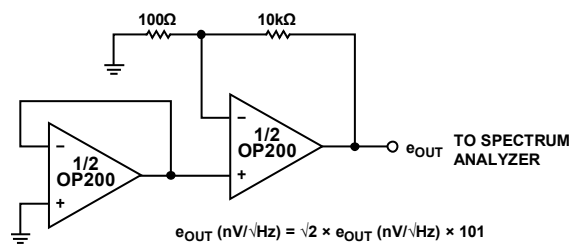


Figure 5. Noise Test Schematic

ABSOLUTE MAXIMUM RATINGS

Table 5.

Parameter	Rating
Supply Voltage	± 20 V
Differential Input Voltage	± 30 V
Input Voltage	Supply voltage
Output Short-Circuit Duration	Continuous
Storage Temperature Range	-65°C to $+150^{\circ}\text{C}$
Lead Temperature (Soldering, 60 sec)	300°C
Junction Temperature Range (T_J)	-65°C to $+150^{\circ}\text{C}$
Operating Temperature Range	
OP200A	-55°C to $+125^{\circ}\text{C}$
OP200E, OP200G	-40°C to $+85^{\circ}\text{C}$

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Table 6.

Package Type	θ_{JA}^1	θ_{JC}	Unit
8-Lead CERDIP (Z Suffix)	148	16	$^{\circ}\text{C}/\text{W}$
8-Lead Plastic DIP (P Suffix)	96	37	$^{\circ}\text{C}/\text{W}$
16-Lead SOIC (S Suffix)	92	27	$^{\circ}\text{C}/\text{W}$

¹ θ_{JA} is specified for worst-case mounting conditions, that is, θ_{JA} is specified for device in socket for CERDIP and PDIP packages; θ_{JA} is specified for device soldered to printed circuit board for SOIC package.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TYPICAL PERFORMANCE CHARACTERISTICS

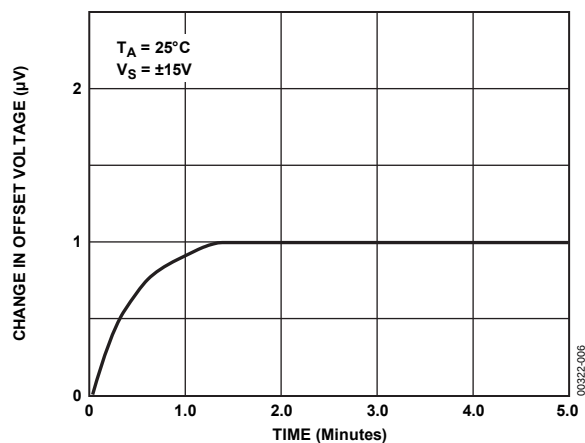


Figure 6. Warm-Up Drift

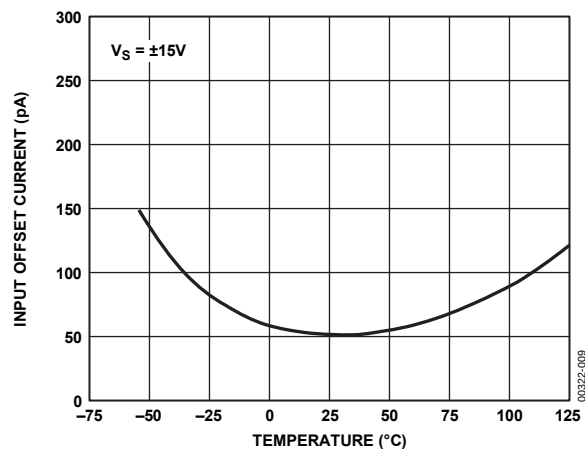


Figure 9. Input Offset Current vs. Temperature

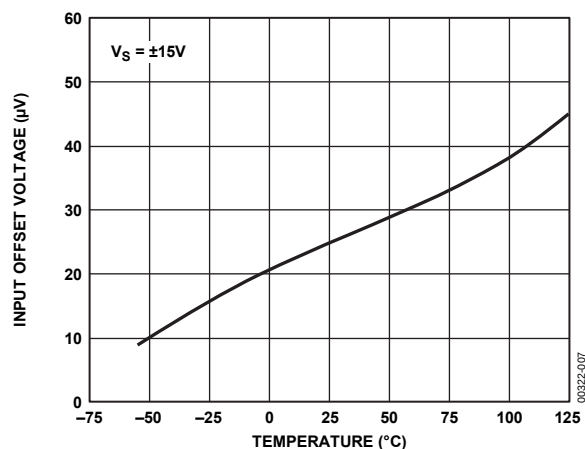


Figure 7. Input Offset Voltage vs. Temperature

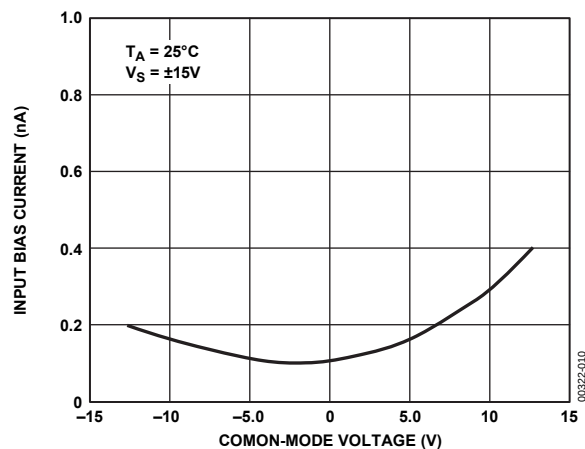


Figure 10. Input Bias Current vs. Common-Mode Voltage

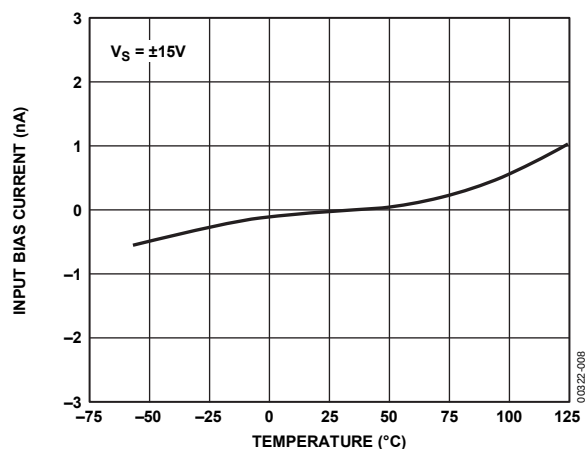


Figure 8. Input Bias Current vs. Temperature

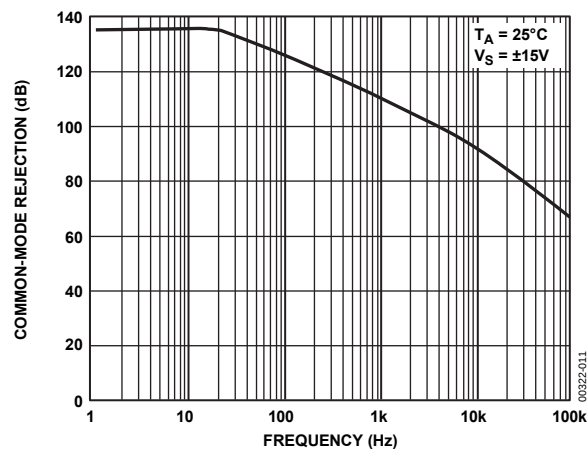


Figure 11. Common-Mode Rejection vs. Frequency

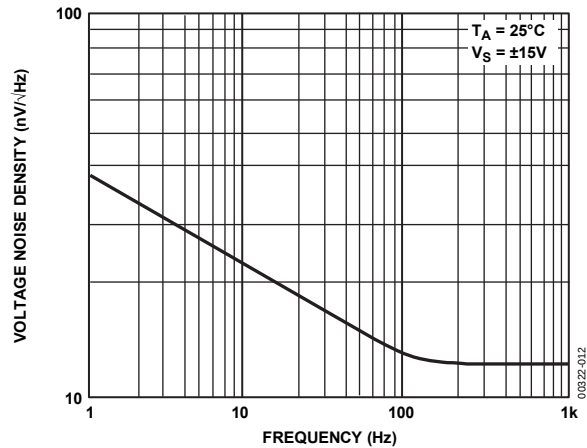


Figure 12. Voltage Noise Density vs. Frequency

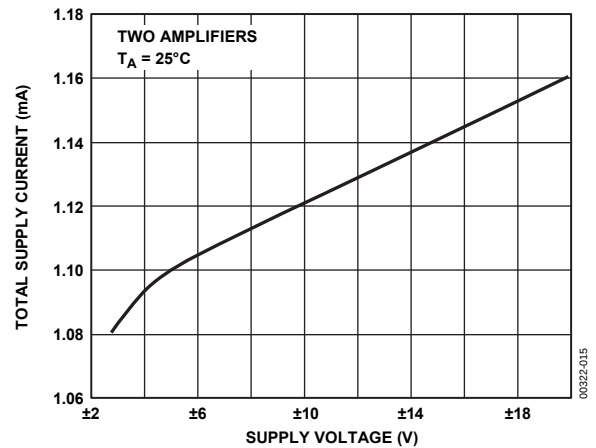


Figure 15. Total Supply Current vs. Supply Voltage

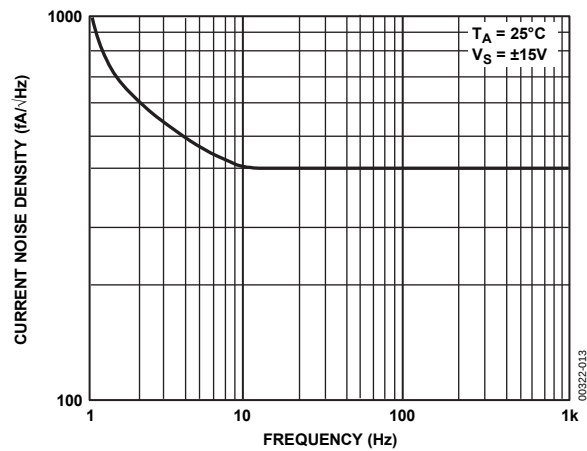


Figure 13. Current Noise Density vs. Frequency

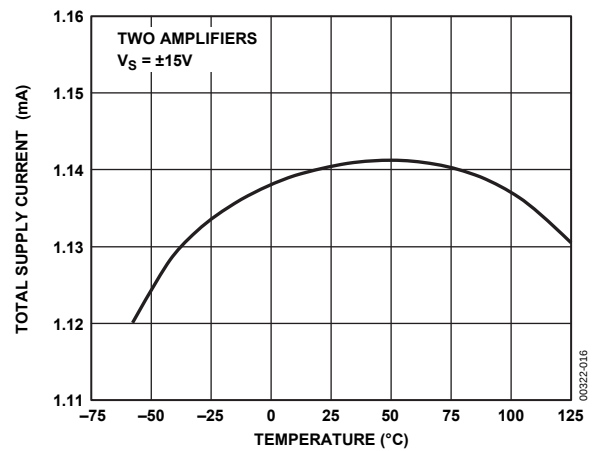


Figure 16. Total Supply Current vs. Temperature

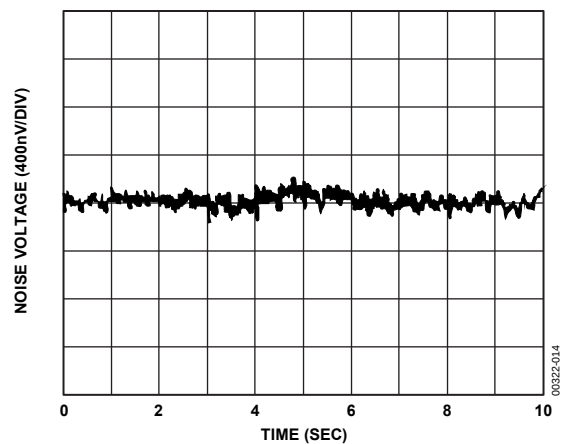


Figure 14. 0.1 Hz to 10 Hz Noise

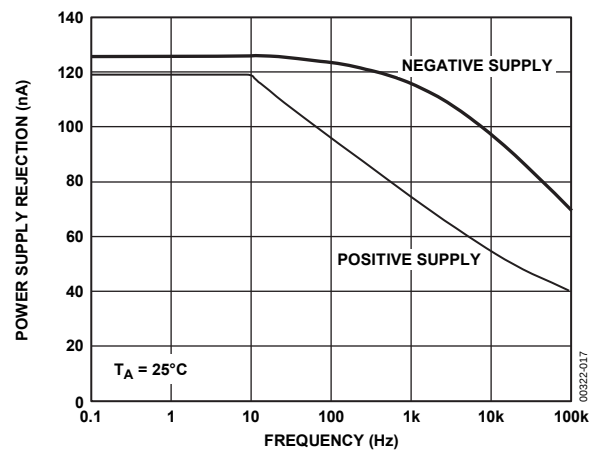


Figure 17. Power Supply Rejection vs. Frequency

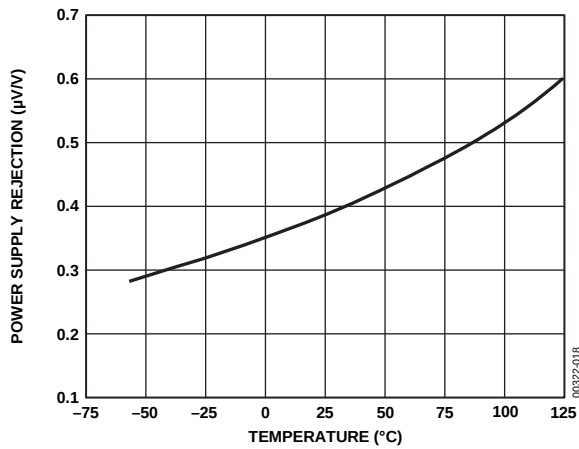


Figure 18. Power Supply Rejection vs. Temperature

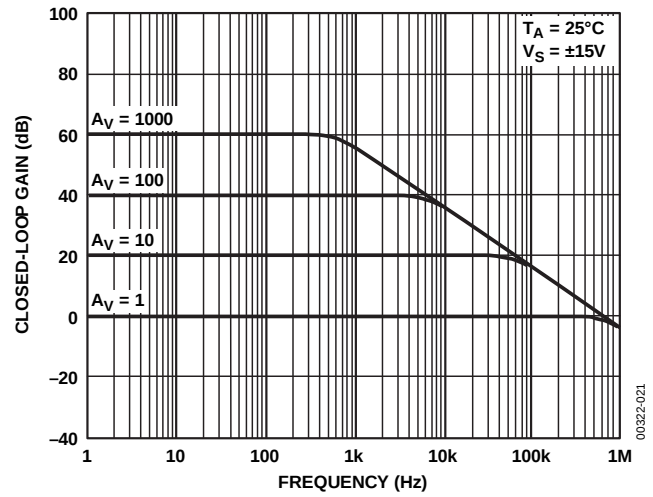


Figure 21. Closed-Loop Gain vs. Frequency

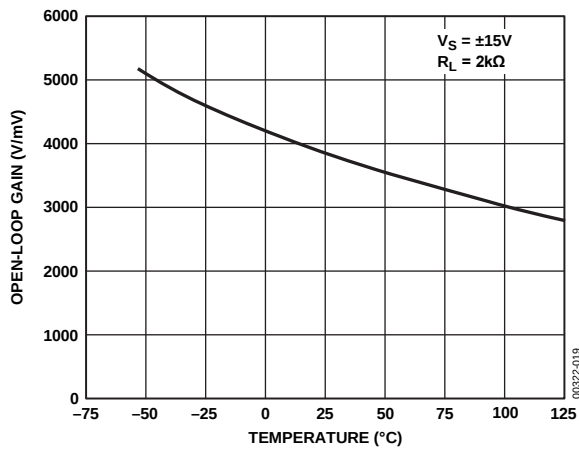


Figure 19. Open-Loop Gain vs. Temperature

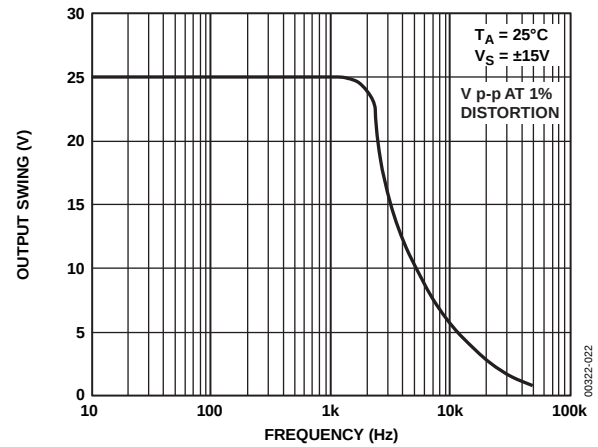


Figure 22. Maximum Output Swing vs. Frequency

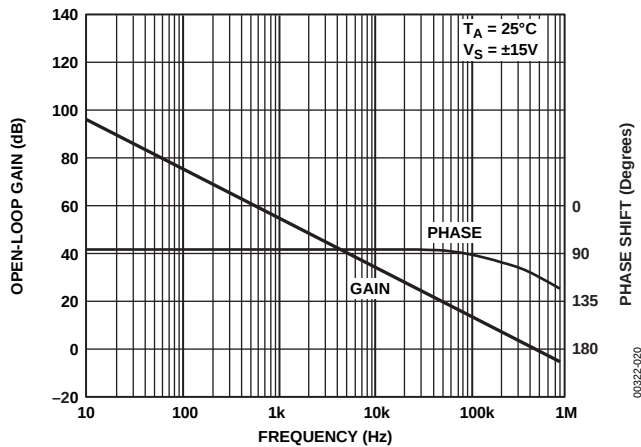


Figure 20. Open-Loop Gain and Phase Shift vs. Frequency

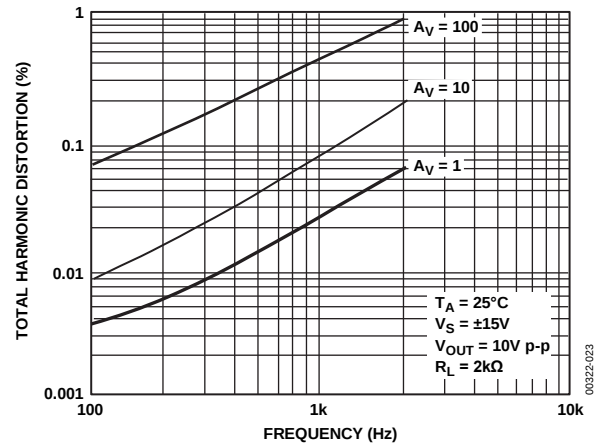


Figure 23. Total Harmonic Distortion vs. Frequency

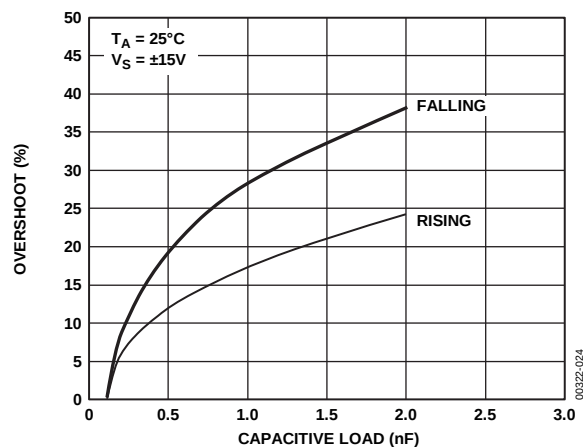


Figure 24. Overshoot vs. Capacitive Load

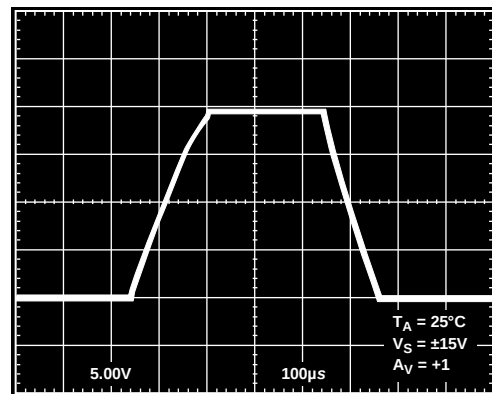


Figure 27. Large Signal Transient Response

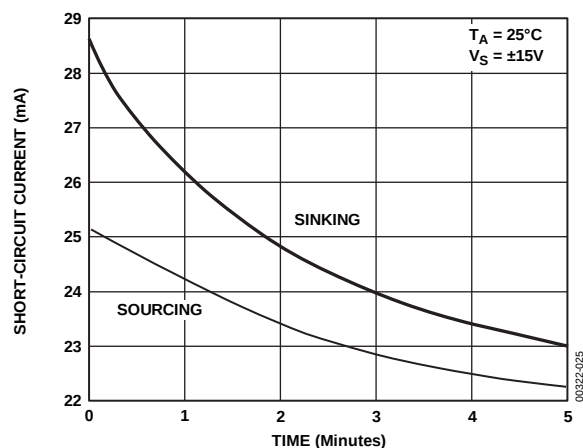


Figure 25. Short-Circuit Current vs. Time

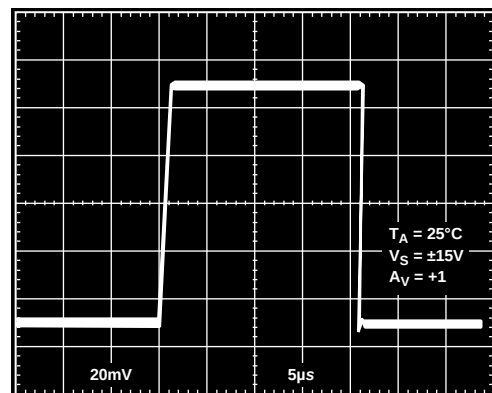


Figure 28. Small Signal Transient Response

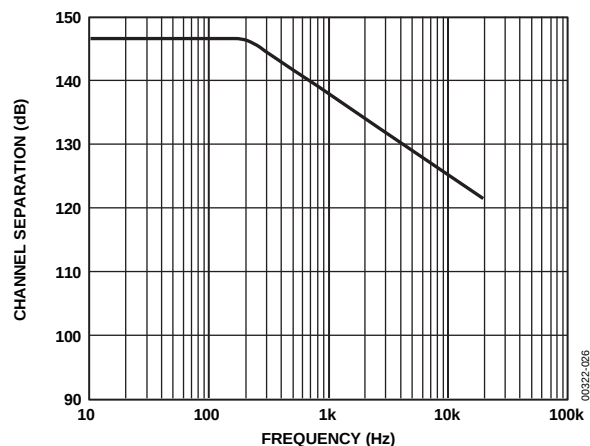
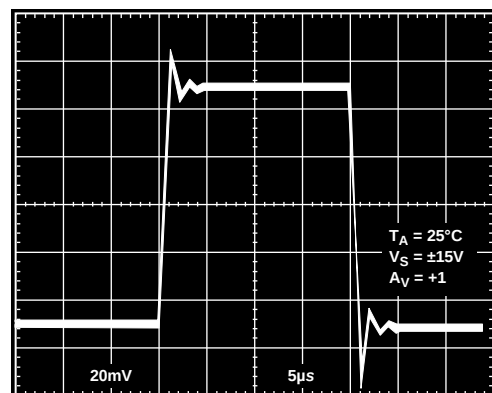


Figure 26. Channel Separation vs. Frequency

Figure 29. Small Signal Transient Response, $C_{LOAD} = 1\text{ nF}$

APPLICATIONS INFORMATION

The OP200 is inherently stable at all gains and is capable of driving large capacitive loads without oscillating. Nonetheless, good supply decoupling is highly recommended. Proper supply decoupling reduces problems caused by supply line noise and improves the capacitive load driving capability of the OP200.

DUAL LOW POWER INSTRUMENTATION AMPLIFIER

A dual instrumentation amplifier that consumes less than 33 mW of power per channel is shown in Figure 30. The linearity of the instrumentation amplifier exceeds 16 bits in gains of 5 to 200 and is better than 14 bits in gains from 200 to 1000. CMRR is above 115 dB (gain = 1000). Offset voltage drift is typically $0.2 \mu\text{V}/^\circ\text{C}$ over the military temperature range, which is comparable to the best monolithic instrumentation amplifiers. The bandwidth of the low power instrumentation amplifier is a function of gain and is shown in Table 7.

Table 7. Gain Bandwidth

Gain	Bandwidth
5	150 kHz
10	67 kHz
100	7.5 kHz
1000	500 Hz

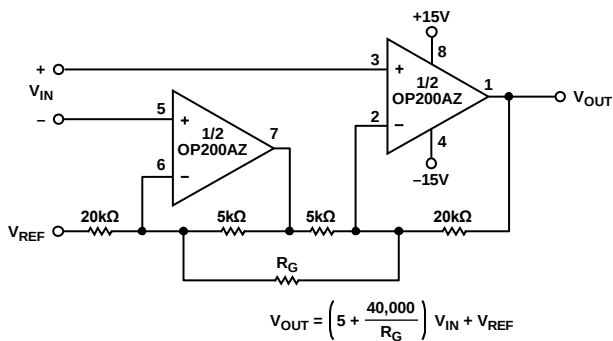


Figure 30. Dual Low Power Instrumentation Amplifier

The output signal is specified with respect to the reference input, which is normally connected to analog ground. The reference input can be used to offset the output from -10 V to $+10 \text{ V}$ if required.

PRECISION ABSOLUTE VALUE AMPLIFIER

The circuit in Figure 31 is a precision absolute value amplifier with an input impedance of $10 \text{ M}\Omega$. The high gain and low TCV_{OS} of the OP200 ensure accurate operation with microvolt input signals. In this circuit, the input always appears as a common-mode signal to the op amps. The CMRR of the OP200 exceeds 120 dB, yielding an error of less than 2 ppm.

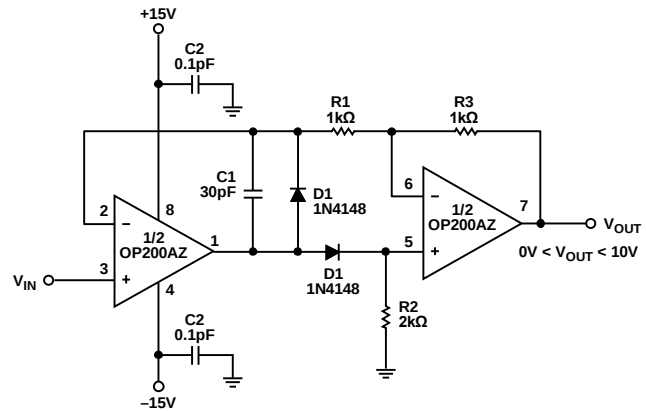


Figure 31. Precision Absolute Value Amplifier

PRECISION CURRENT PUMP

The maximum output current of the precision current pump shown in Figure 32 is $\pm 10 \text{ mA}$. Voltage compliance is $\pm 10 \text{ V}$ with $\pm 15 \text{ V}$ supplies. Output impedance of the current transmitter exceeds $3 \text{ M}\Omega$ with linearity better than 16 bits.

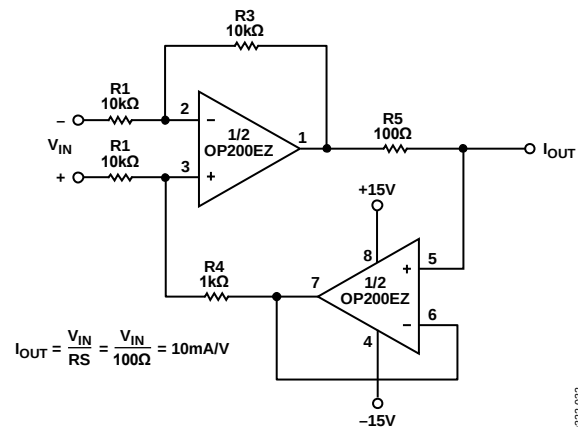


Figure 32. Precision Current Pump

DUAL 12-BIT VOLTAGE OUTPUT DAC

The dual output DAC shown in Figure 33 is capable of providing untrimmed 12-bit accurate operation over the entire military temperature range. Offset voltage, bias current, and gain errors of the OP200 contribute less than 1/10 of an LSB error at 12 bits over the military temperature range.

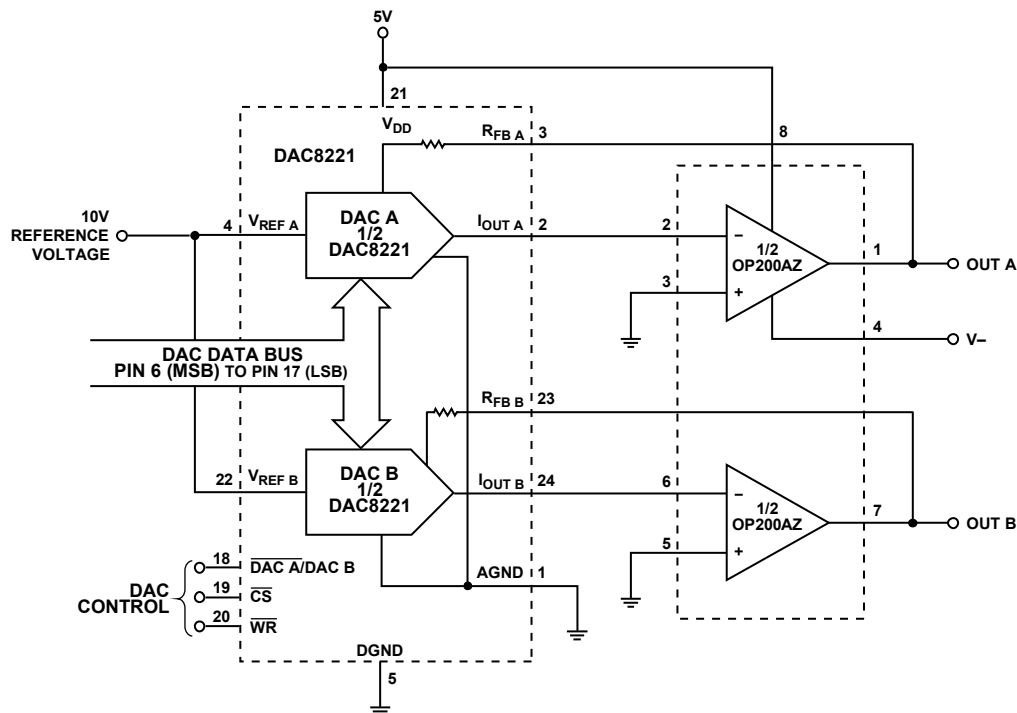


Figure 33. Dual 12-Bit Voltage Output DAC

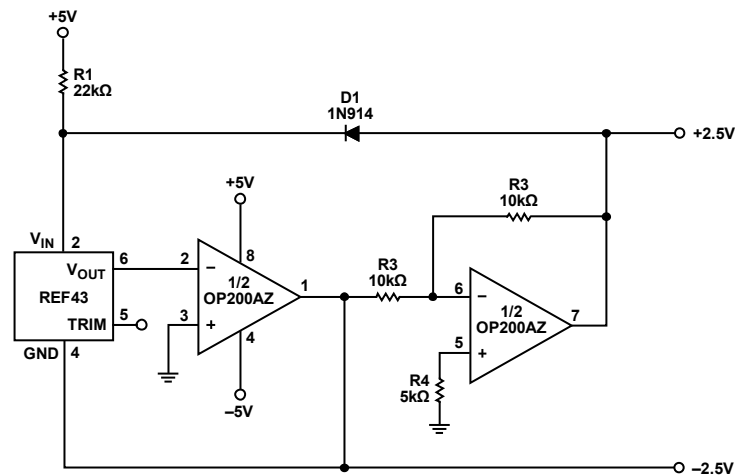


Figure 34. Dual Precision Voltage Reference

PROGRAMMABLE HIGH RESOLUTION WINDOW COMPARATOR

The programmable window comparator shown in Figure 35 is easily capable of 12-bit accuracy over the full military temperature

range. A dual CMOS 12-bit DAC, the [DAC8221](#), is used in the voltage switching mode to set the upper and lower thresholds (DAC A and DAC B, respectively).

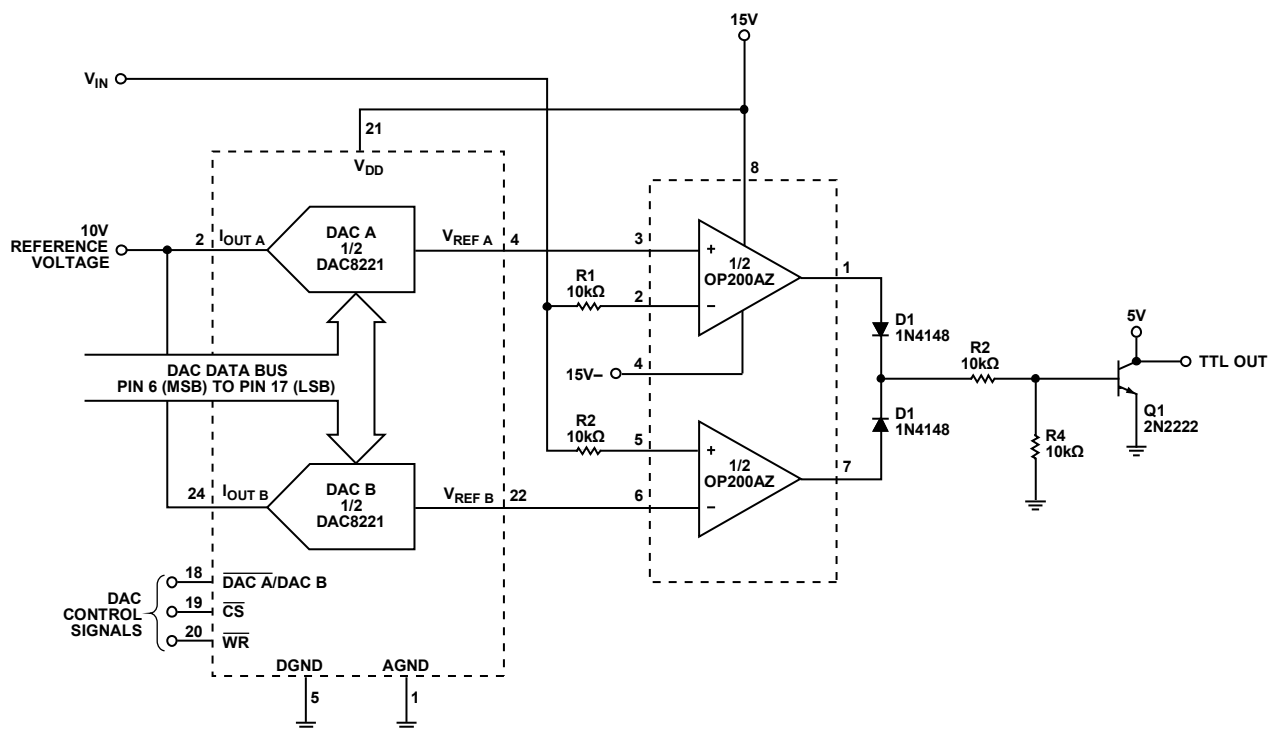
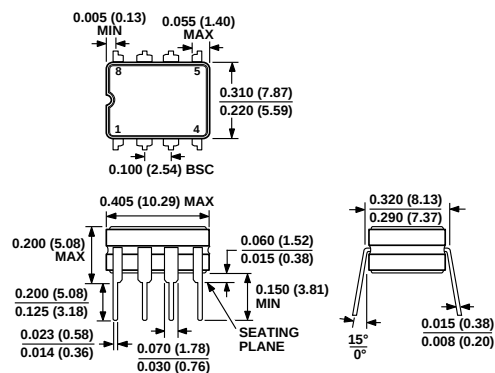


Figure 35. Programmable High Resolution Window Comparator

00322-035

OUTLINE DIMENSIONS

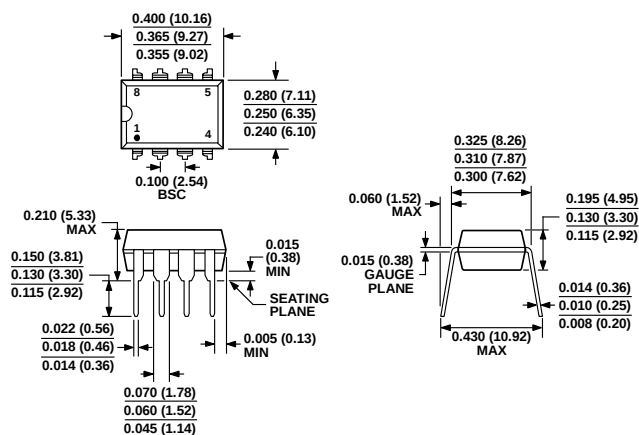


CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 36. 8-Lead Ceramic Dual In-Line Package [CERDIP]
(Q-8)

Z-Suffix

Dimensions shown in inches and (millimeters)



COMPLIANT TO JEDEC STANDARDS MS-001

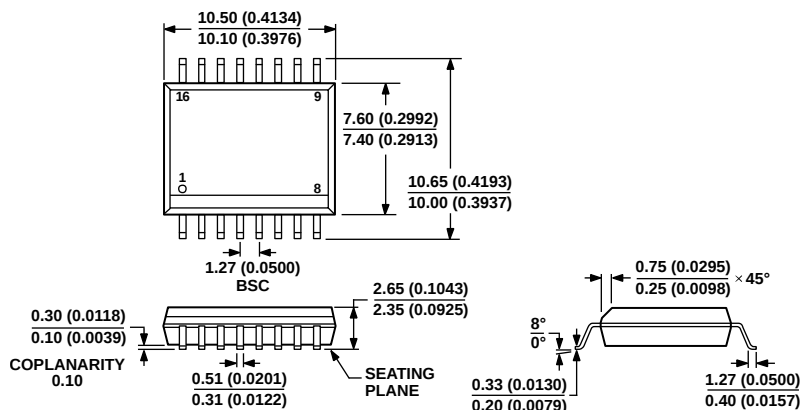
CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN. CORNER LEADS MAY BE CONFIGURED AS WHOLE OR HALF LEADS.

Figure 37. 8-Lead Plastic Dual In-Line Package [PDIP]
(N-8)

P-Suffix

Dimensions shown in inches and (millimeters)

071606-A



COMPLIANT TO JEDEC STANDARDS MS-013-AA
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

03-27-2007-B

Figure 38. 16-Lead Standard Small Outline Package [SOIC_W]
Wide Body
(RW-16)
S-Suffix

Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model ¹	T _A = 25°C V _{OS} Max (μV)	Temperature Range	Package Description	Package Option
OP200AZ	75	–55°C to +125°C	8-Lead CERDIP	Z-Suffix (Q-8)
OP200EZ	75	–40°C to +85°C	8-Lead CERDIP	Z-Suffix (Q-8)
OP200GPZ	200	–40°C to +85°C	8-Lead PDIP	P-Suffix (N-8)
OP200GSZ	200	–40°C to +85°C	16-Lead SOIC_W	S-Suffix (RW-16)
OP200GSZ-REEL	200	–40°C to +85°C	16-Lead SOIC_W	S-Suffix (RW-16)

¹ The OP200GPZ, OP200GSZ, and OP200GSZ-REEL are RoHS Compliant Parts.